HP Business Critical Systems Technology Update

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Common Modular Infrastructure





Mission-Critical Customer Challenges

Financial Services
Every minute of
downtime = a minute of
lost revenue!



Manufacturing and Distribution Production comes to grinding halt



Healthcare
Patient outcomes
depend on 24x7
access to data



Public Sector and CME Customer retention and fraud detection at risk



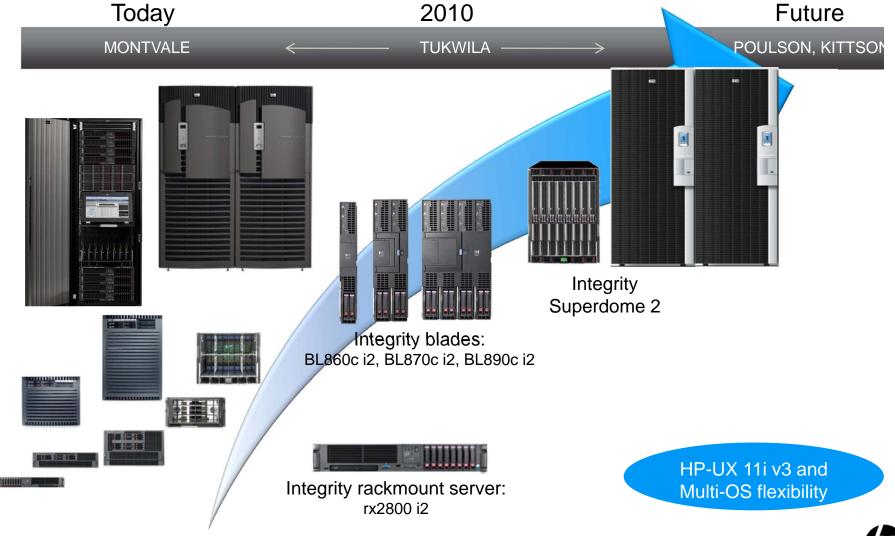
No tolerance for downtime

Increasing SLAs with decreasing budgets

Islands of legacy apps and monolithic systems

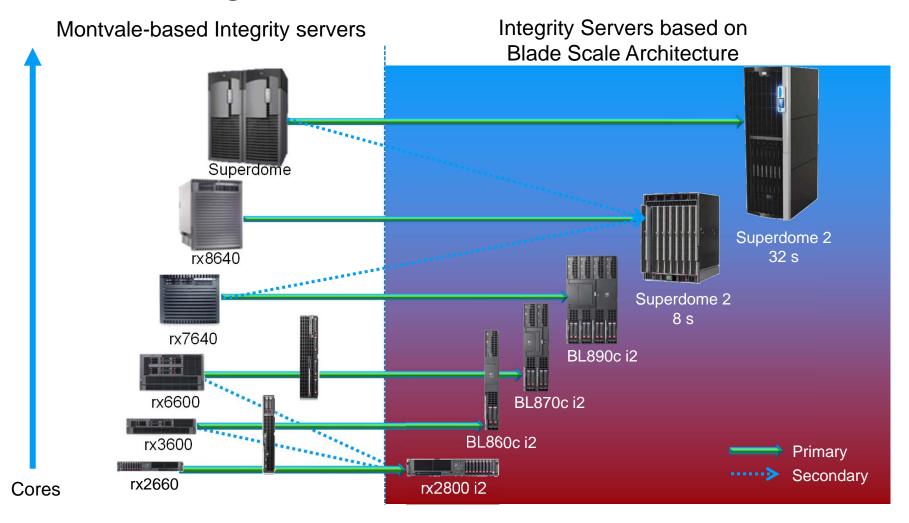


HP Next Generation Integrity Servers





Positioning the New vs. Current Servers



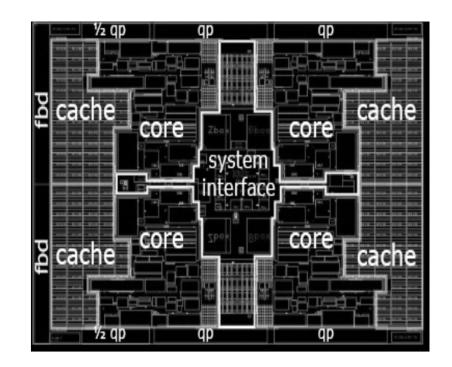
>2x performance per socket and much better price/performance



Intel® Itanium® Processor 9300 Series (Tukwila)

World's First 2 Billion Transistor Processor Is Here

- Four CPU cores with enhanced multithreading (8 threads per processor)
- >2x performance per socket vs. dualcore Itanium® Processor 9100 series
- 30MB on-die cache
- Intel® QuickPath Interconnect point-topoint bidirectional links for CPU-CPU and CPU-IO communication
- Dual integrated memory controllers with Scalable Memory Interconnect
- Advanced RAS (hardened latches, enhanced error detection/correction and error handling capabilities)
- Energy management features (enhanced demand-based switching, Intel ® Turbo Boost Technology)

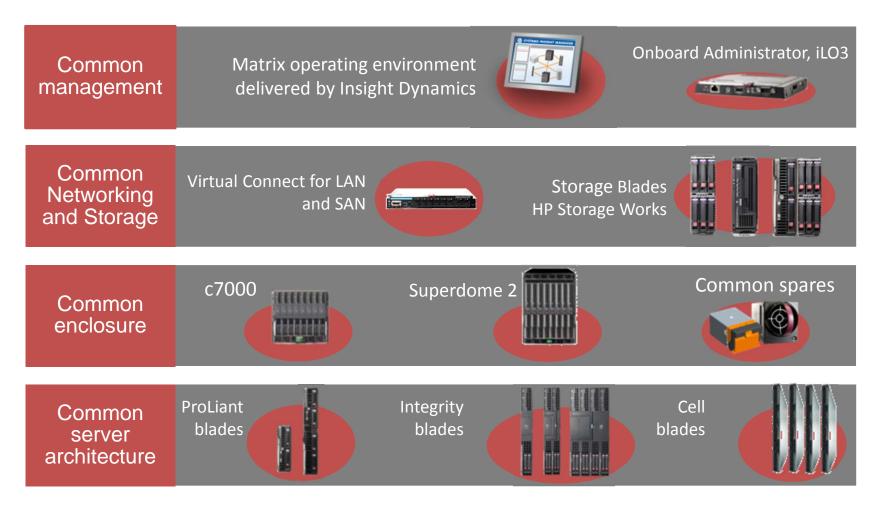


Intel® Itanium® Platform Roadmap

Tukwila Processor Intel® Itanium® (Intel® Itanium® Kittson **Poulson** Generation **Processor 9100 Series** (In Planning) **Processor 9300 Series)** Chipset 870/OEM Boxboro/OEM Advanced Multi-Core Dual Core Quad Core, 30MB Total Cache, Architecture Hyper-Threading Technology 24MB Shared Cache Hyper-Threading 9th Itanium® Intel QuickPath Interconnect **Enhancements** Hyper-Threading **Product** Technology **Dual Integrated Memory** Instruction-Level New Controllers, 4 Channels Advancements Intel Virtualization Technologies/ **Technology** Next Gen IO (PCIe Gen 2) **Capabilities** 32nm Process Compatible **Technology** with Tukwila Mainframe-Class RAS Intel Cache Safe **Platforms Technology** Large On-Die Cache **Enhanced Virtualization** New RAS Features Lock-step Data Integrity Scalable • Common Chipset w/ Intel® Buffered **Technology** Xeon® NHM-EX Processor Compatible with Tukwila Memory **Platforms DBS** Power Voltage Frequency Mgmt Management Scalable Buffered Scalable Buffered Memory **Technology** Memory **Targeted** Enterprise Business (Database, Business Intelligence, ERP, HPC, ...) Segments 2010 2007 Future Future

Common Modular Building Blocks

Simplicity through standardization

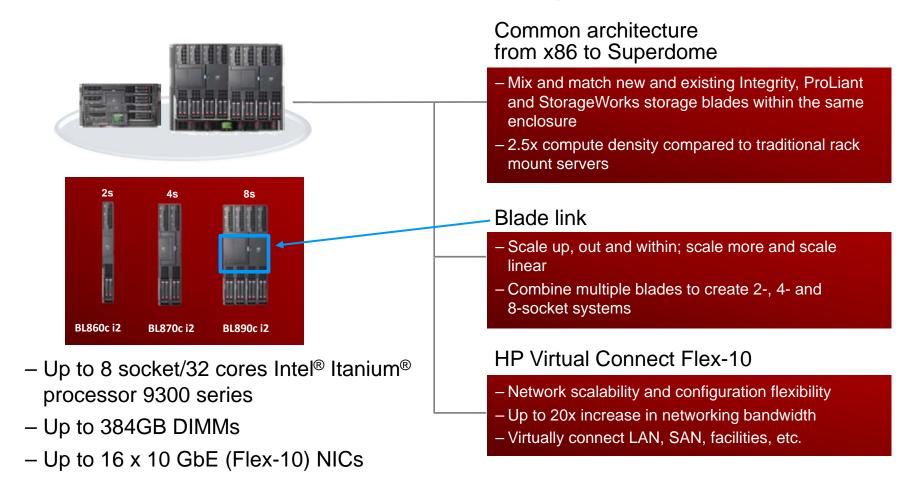






Introducing BL8x0c i2 Server Blades

World's first scale-up blades built on the industry's #1 blade infrastructure



Flexible mission-critical server blades combined with the efficiency of HP BladeSystem to accelerate IT effectiveness



Introducing New Integrity Server Blades

BL860c i2, BL870c i2 and BL890c i2

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	BL860c i2	BL870c i2	BL890c i2
Processor	Intel® Itanium® processor 9300 series (quad-core)		
Processors/Cores	Up to 2 Processors/8 cores	Up to 4 Processors/16 cores	Up to 8 Processors/32 cores
Chipset		Intel Boxboro Chipset (I/O Hub)	
Memory Industry Std. DDR3 technology	24 DIMM Sockets 96GB max (with 4GB DIMMs)	48 DIMM Sockets 192GB max (with 4GB DIMMs)	96 DIMM Sockets 384GB max (with 4GB DIMMs)
Internal Storage	2 Hot-Plug SFF SAS HDDs HW RAID 0/1 controller (standard)	4 Hot-Plug SFF SAS HDDs HW RAID 0/1 controller (standard)	8 Hot-Plug SFF SAS HDDs HW RAID 0/1 controller (standard)
Networking (integrated)	4 x 10 GbE (Flex-10) NICs	8 x 10 GbE (Flex-10) NICs	16 x 10 GbE (Flex-10) NICs
Mezzanine Slots	3 PCIe slots	6 PCIe slots	12 PCIe slots
Management	Integrity Integrated-Lights Out 3 (iLO 3) Advanced Pack (standard)		
Density	8 server blades in c7000 4 server blades in c3000	4 server blades in c7000 2 server blades in c3000	2 server blades in c7000 1 server blade in c3000
Warranty		3 Year (Next Business Day, 9x5)	

Unique HP Integrity Blade Link Technology

Simplified scalability with industry's first 2, 4, 8-socket HP-UX server blades

Combines multiple blades into a single, scalable system



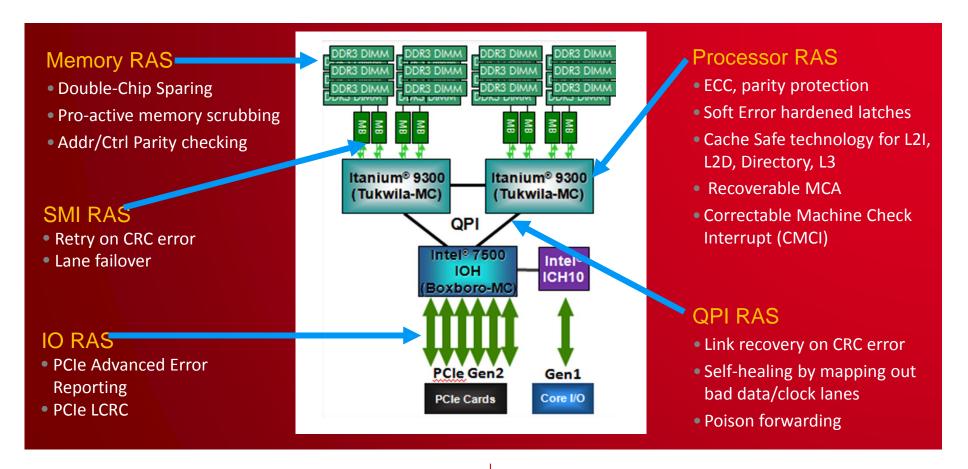
8-socket system at 2x the performance in half the footprint



Closer look at Integrity Server Resiliency



Always-on Platform Design



Double-chip sparing

Provides 17x better reliability than Single-Chip Sparing Itanium processor

Provides 2x better reliability than industry volume CPUs

Introducing Superdome 2

The ultimate mission-critical consolidation platform



- Up to eight 2s cell blades (16s/enclosure)
- 32 DIMM sockets (2TB with 8GB DIMMS)
- Up to 24 mezz. & 96 stand up I/O slots
- 18U in standard HP Rack
 - 64s capable with 4 base enclosures
 - Programmable active door display

Common architecture from x86 to Superdome

- Common spares: power supplies, fans & I/O
- Modular, front-back serviceable racks
- Common management for entire infrastructure
- Zero-to-managed in minutes

Superdome 2 Crossbar Fabric for extreme scalability and reliability

- Independent I/O scaling to meet any workload
- Only Unix system with end-to-end multi-pathing
- Boosts infrastructure reliability by up to 450%

Power-on-once technology

- Superdome 2 analysis engine: proactive error detection and prescriptive recommendations
- End-to-end transaction retry: transactions tracked, retried and rerouted to completion
- Online optimization and repair: tool-free serviceability + single-click firmware upgrades

Extreme scalability, on-demand modularity, unquestioned reliability



Superdome 2 Cell Blades

Value and Key Features

Processor/ Chipset	1-2 Quad-Core Intel® Itanium® Tukwila processors HP sx3000 chipset 2-256 core SMP capable
Memory	Industry standard DDR3 technology -32 DIMM Sockets -256GB max (with 8GB DIMMs)
Form Factor	~23.0"H x 2.0"W x 19.6"D
Networking	Four integrated 10GE NICs
I/O	Three embedded PCI-E (x8) Mezz. Slots
Management	Management Processor with iLO3 (Integrated Lights Out functionality)



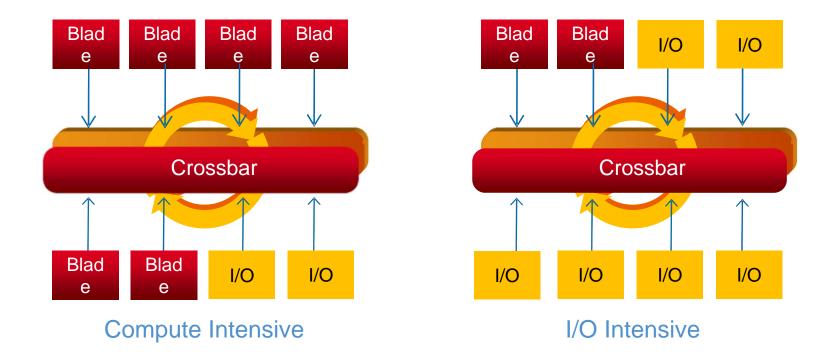
Key Points:

- Fault-tolerant Fabric for breakthrough levels of reliability and availability
- Modular, cell-blade design for simplified management and ease of scalability
- HP sx3000 chipset



Superdome 2 Crossbar Fabric

Fault tolerant reliability + flexible and cost effective scaling



- Only Unix server to scale I/O independently from CPU
- Only Unix server with end-to-end redundant data paths



Superdome 2

Value and Key Features

Cell Blades/ Processors	Up to Eight 2S Superdome Cell Blades per enclosure 2-64 socket capable (1-4 enclosures)
Memory	-2TB memory capacity (per enclosure, 8GB DIMMS)
Form Factor	18U in standard HP rack
Networking	32 integrated 10Gigabit Ethernet NICs 8 switch bays 1GE Manageability LAN
I/O Slots	24 Mezzanine slots Up to 96 stand-up I/O slots with IO expansion
Management	Onboard Administrator: HP Insight display
Partitioning	8 nPars (up to 32 with 4 enclosures) vPars (16 per nPar), HPvm



Key Points

- Mission-critical value, with breakthrough levels of reliability and availability
- Dynamic scalability + virtualization of widest range of IT resources
- "Power-on-Once" robustness
- Simplified, common management environment
- Efficient and green, from chip to chiller
- Modular, infrastructure building blocks



Superdome 2

Adaptive Cell Infrastructure

4 max IOX



8S 8 Blades (18U+4U,19" rack)

Tukwila

16 Sockets

64 Cores

128 Threads

4 TB Memory

32 LOM NICs 10 GbE

24 Mezzanine PCI-E

96 IOX PCI-E

8 max IOX (4U)



16S 8 Blades (18U+4U,19" rack)

Tukwila

16 Sockets

64 Cores

128 Threads

4 TB Memory

32 LOM NICs 10 GbE

24 Mezzanine PCI-E

96 IOX PCI-E

IOX (4U)

8 max

32S <u>Cabled (2xB16)</u> 16 Blades (36U, 19" racks)

Tukwila
32 Sockets
128 Cores
256 Threads
8 TB Memory
64 LOM NICs 10 GbE
48 Mezzanine PCI-E
96 IOX PCI-E

IOX (4U)

8 max

64S
<u>Cabled (4xB16)</u>
32 Blades
(36U, dual 19" racks)

Tukwila

64 Sockets

256 Cores

512 Threads

16 TB Memory

128 LOM NICs 10 GbE

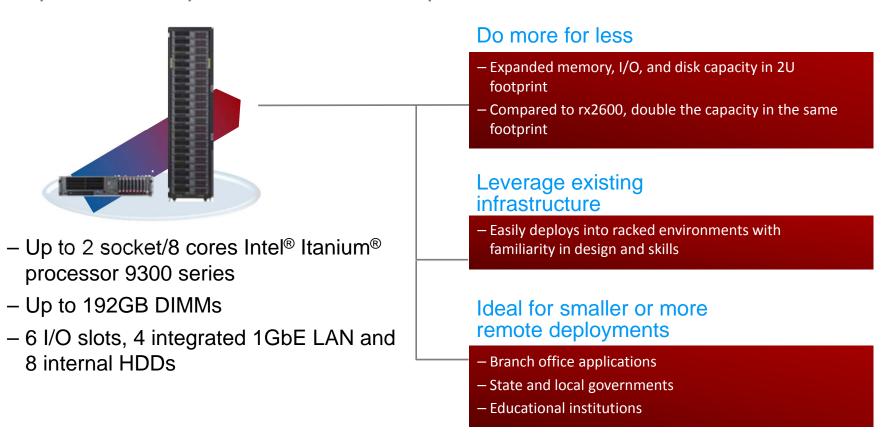
96 Mezzanine PCI-E

96 IOX PCI-E



Introducing rx2800 i2

Superdome-inspired 2U rackmount platform



8-core scalability in 3x less compute density without sacrificing RAS



rx2800 i2 – 2p Rackmount

Value and Key Features

rx2800 i2		
Processor	Up to two Dual-Core or Quad-Core Intel® Itanium® (Tukwila) processors	
Memory	Industry standard DDR3 technology 24 PC3-8500 DIMM sockets 192GB max (with 8GB DIMMs)	
Internal Storage	8 Hot-Plug SFF Serial Attached SCSI HDDs 1 CD+RW or DVD+RW	
Networking	Dual Integrated Gigabit Ethernet ports Manageability LAN	
I/O Slots	6 PCI-E slots	
Management	Management Processor with iLO3 (Integrated Lights Out functionality)	
Form Factor	2U Rack Mount Server (office tower conversion kit available)	



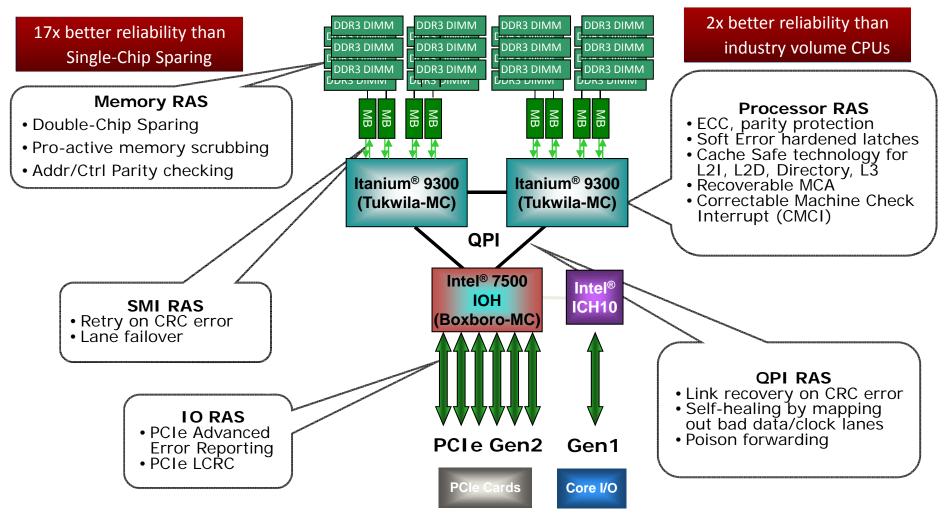
Key Points:

- Affordable, 8-core scalable entry-level non-x86 server
- High Density Compute Server (2U footprint)
- Excellent memory capacity
- Continued innovations in RAS
- Ease to deploy into today's racked environments



rx2800 i2 Platform RAS

Always-On Resiliency





The HP ProLiant DL980 G7

HP PREMA Architecture to scale up with confidence

Self-healing Resiliency

- 200% boost in server availability
- Redundant system fabric to maximize uptime

Balanced Scaling

- -World record performance enabled by HP Smart CPU caching
- -Up to 8 Intel® Xeon® 7500 series processors
- -Up to 8 cores and 24MB L3 cache per processor
- -Up to 128 DDR3 DIMM slots; 2.0TB max memory!
- -Up to 16 slots, PCI-E 2.0 or PCI-X
- -Quad-Port 1GbE embedded NIC upgradable to Dual Port 10GbE

Breakthrough Efficiency

- -Consolidate up to 197 legacy servers on to a single system
- -HP-only innovations like Thermal Logic, Sea of Sensors, and Dynamic Power Capping for ROI that competitors can't touch
- -iLO3 & Insight Control for tomorrow's datacenter capabilities today





The HP ProLiant DL980 G7

How the platform delivers performance & availability

Scale-up Performance

- 128 logical CPUs
 - 8 x 8 x 2 (Hyper Threading)
 - o 24MB shared L3 cache
- Up to 2 TB DDR3 RAM
 - o At 1066 GHz
- Expandable PCIe v2 capacity
- Improved scalability
 - QPI and HP developed Node Controller
 - o QPI Perf: 25.6 GB/s per link pair
- Error recovery thresholds

Scale-up Availability

- Spare wires for signal & data paths
- Spare wire failover for clock
- Self-healing data paths
- Memory Mirroring
- Memory Sparing
- Memory scrubbing
 - Demand scrubbing
 - Patrol scrubbing*
- Poison data discovery and containment
- Machine Check Architecture
 - · Containment & Recovery
- PCI AER Recovery*

Scale-up Behavior

- Retry during transient errors
- CRC & ECC protection for links
- Error logging (fast problem resolution)
 - MCAs
 - CRC errors
 - ECC errors
 - o Parity errors
 - PCI AERs
 - o Thresholds reached
- Configurable error recovery thresholds

^{* =} Post release capability

HP ProLiant DL980 G7

Overview



ProLiant DL980 G7		
Processor	 4p or 8p, up to 8-core Nehalem EX processors Drop-in upgrade to Westmere EX 	
Memory	128 DDR3 DIMM slots2TB max memory (w/ 16GB DIMMs)	
Internal Storage	8 SFF SAS drive baysEmbedded RAID support1 DVD removable drive bay	
Networking	Four embedded Gbit NICs	
I/O	 5 - pci-e Gen 2 I/O slots standard, (2 - x8 & 3 - x4) Optional I/O expander for up to 11 additional slots One full length option with 6 slots One low profile option with 5 slots 	
Management	• iLO 3	
Form Factor	8U Rack Mount Server	
OS	Windows, Linux, Sun Solaris	
Virtualization	 VMWare ESX, Microsoft HyperV, Linux Virtualization, Oracle VM 	



Integrity Integrated Lights-Out 3 (iLO 3)



Embedded remote management built into every system

Basic Features:

- "Always on" remote access to server health, status, and event log
- Command line and web GUI interfaces
- Private management LAN interface with Secure Shell (SSH)
- Virtual serial port console
- Virtual power on/off/reset control

Advanced Features (no license key required, factory enabled in all Integrity systems)

- Virtual Media CD/DVD-ROM
- iLO Power Regulation (OS controlled)
- Integration with Insight power management
- LDAP authentication services



Scalable Integrity iLO 3 architecture grows with your system

An iLO 3 physically on every Integrity server blade, automatically grows with multi-bladed modular servers



Everything you need is built-in

iLO 3 Advanced Pack license is built into every Integrity server, no additional licensing is needed



Everything you need is built-in

iLO 3 Advanced Pack license is built into every Integrity server, no additional licensing is needed



HP-UX 11i v3



HP-UX 11i v3

Ensure availability | accelerate innovation | simplify operations

Integrated Operating Environments

Complete integrated data center, high availability and virtual server environments

Comprehensive Security

Industry validated UNIX * security that meets the most stringent of standards

Mission Critical Virtualization

Rich portfolio of virtualization capabilities, Insight Dynamics-VSE and Utility pricing

#1 rated by Unix users for availability, performance, and management



HP-UX 11i v3: High-Level OE

Functionality

Data Center Operating Environment - <u>DC-OE</u> Integrated mission-critical UNIX® virtualization

High Availability OE

HA-OE

Availability clusters

Basic disaster recovery

Availability toolkits for databases and internet servers

Intuitive cluster management

Performance analysis: system level

Advanced file system and volume management

Base OE

UNIX® kernel plus:

System & power management

Networking

Secure resource & hard partitions

Security - systems, data, & identity; auditing tools

Performance analysis: Kernel, processes & applications

Base file system & volume manager

HP-*W*/11i v3

Virtual Server OE VSE-OE

Soft or sub-CPU partitions

Capacity planning

Goal-based workload management

Advanced infrastructure management

Performance analysis: system level

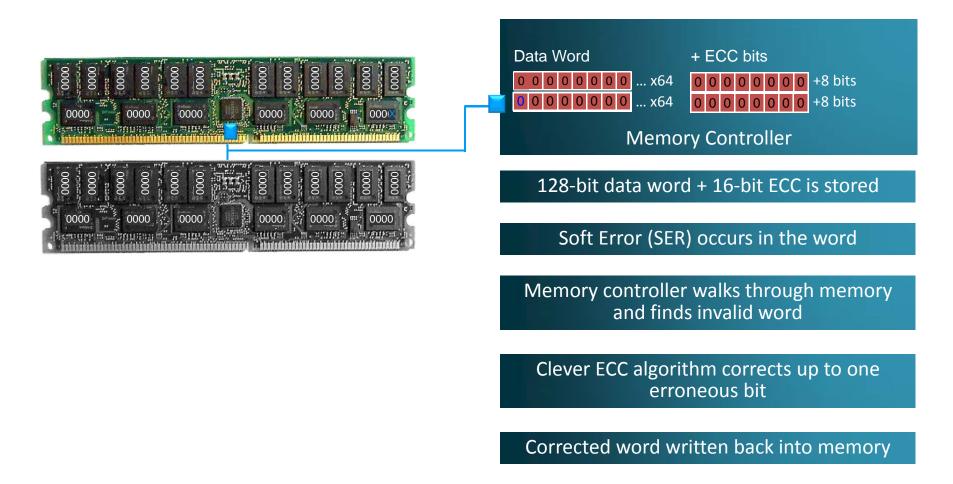
Advanced file system and volume management



Outcomes that matter.

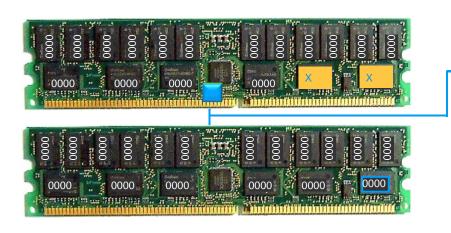


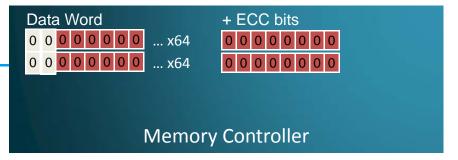
Proactive Scrubbing and ECC Explained



Scrubbing and basic ECC protect the memory system from all single-bit errors and protect the system from multiple errors accumulating.

Double-Chip Sparing Explained





128-bit data words + 16-bit ECC stored so

Entire chip fails, memory controller reads it

Memory controller ECC corrects it on read

Writes the failed chip contents to spare bits

Another chip in the rank fails, not necessarily on the same DIMM, and the memory controller reads it

Memory controller ECC corrects it on read

Double-chip sparing provides 1/17th the repair rate, and 1/3rd less memory downtime compared to single-chip sparing.